

# APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

Microwave MLCC with Narrow-Tolerance (UF)

0402 Size (25V & 50V)

NP0 Dielectric

Halogen Free & RoHS Compliance

\*Contents in this sheet are subject to change without prior notice.

## 1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC UF series MLCC is used at high frequencies generally have a small temperature coefficient of capacitance, typical within the ±30ppm/°C required for NP0 (C0G) classification, Ultra-narrow tolerance of capacitance and have excellent conductivity internal electrode. Thus, WTC UF series MLCC will be with the feature of low ESR and high Q characteristics.

## 2. FEATURES

- a. High Q and low ESR performance at high frequency.
- b. Ultra low capacitance to 0.05pF.
- c. Can offer ultra-narrow tolerance to ±0.02pF.
- d. Quality improvement of telephone calls for low power loss and better performance.

# 3. APPLICATIONS

- a. Telecommunication products & equipments: Mobile phone, WLAN, Base station.
- b. RF module: Power amplifier, VCO.
- c. Tuners.

# **4. HOW TO ORDER**

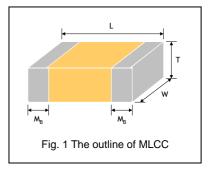
<u>UF</u>	<u>15</u>	<u>N</u>	<u>R05</u>	<u>P</u>	<u>250</u>	<u>C</u>	I
<u>Series</u>	<u>Size</u>	Dielectric	<u>Capacitance</u>	Tolerance	Rated voltage	<u>Termination</u>	<u>Packaging</u>
<b>UF</b> = Microwave MLCC with narrow-tolerance	<b>15</b> =0402 (1005)	N=NP0	Two significant digits followed by no. of zeros. And R is in place of decimal point.	P=±0.02pF Q=±0.03pF A=±0.05pF B=±0.1pF	Two significant digits followed by no. of zeros. And R is in place of decimal point.	C=Cu/Ni/Sn	T=7" reeled G= 13" reeled
			eg.: R05=0.05pF 0R5=0.5pF 1R0=1.0pF	ogy cor CORPORATION	<b>250</b> =25 VDC <b>500</b> =50 VDC		



# **5. EXTERNAL DIMENSIONS**

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sym	bol	Remark	M <sub>B</sub> (mm)
0402 (1005)	1.00±0.05	0.50±0.05	0.50±0.05	N	#	0.25+0.05/-0.10

<sup>#</sup> Reflow soldering only is recommended.



# **6. GENERAL ELECTRICAL DATA**

Dielectric	NP0	
Size	0402	
Capacitance*	0.05pF to 3pF	
Capacitance tolerance	P (±0.02pF ), Q (±0.03pF), A (±0.05pF ), B (±0.1pF)	
Rated voltage (WVDC)	25V, 50V	
Q**	Q≥400+20C	
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F whichever is smaller.	
Operating temperature	-55 to +125°C	
Capacitance change	±30ppm/℃	
Termination	Ni/Sn (lead-free termination)	

<sup>\*\*</sup> Measured at the conditions of 25℃ ambient tempe rature and 30~70% related humidity. Apply 1.0±0.2Vrms, 1.0MHz±10%

# 7. PACKAGING DIMENSION AND QUANTITY

Size	Thiskness (mm)/Symbol	Paper tape	
Size	Thickness (mm)/Symbol	7" reel	13" reel
0402 (1005)	0.50±0.05	10,000	50,000

Unit: pieces

# **8. CAPACITANCE RANGE**

DIELECTRIC		N		
SIZE		04	Tolerance	
RATED VOLTAGE (VDC)		25	25 50	
	0.05pF (R05)	N	N	P, Q, A
	0.1pF (0R1)	N	N	P, Q, A
	0.2pF (0R2)	N	N	P, Q, A
	0.3pF (0R3)	N	N	P, Q, A
	0.4pF (0R4)	N	N	P, Q, A
	0.5pF (0R5)	N	N	P, Q, A
	0.6pF (0R6)	N	N	P, Q, A
	0.7pF (0R7)	N	N	P, Q, A
	0.8pF (0R8)	N	N	P, Q, A
Capacitance	0.9pF (0R9)	N	N	P, Q, A
ital	1.0pF (1R0)	N	N	P, Q, A
bac	1.1pF (1R1)	N	N	A, B
Cal	1.2pF (1R2)	N	N	A, B
	1.3pF (1R3)	N	N	A, B
	1.5pF (1R5)	N	N	A, B
	1.6pF (1R6)	N	N	A, B
	1.8pF (1R8)	N	N	A, B
	2.0pF (2R0)	N	N	A, B
	2.2pF (2R2)	N	水村 s	A, B
	2.4pF (2R4)	N	E PILA	A, B
	2.7pF (2R7)	N // T	ドンル化く	A, B
	3.0pF (3R0)	N /	SYNTH B	A, B

<sup>1.</sup> The letter in cell is expressed the symbol of product thickness.

<sup>2.</sup> For more information about products with special capacitance or other data, please contact WTC local representative.



## **Multilayer Ceramic Capacitors**

## **Approval Sheet**

# 9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Conditions	Requirements
1.	Visual and		* No remarkable defect.
	Mechanical		* Dimensions to conform to individual specification sheet.
2.	Capacitance	1.0±0.2Vrms, 1MHz±10%	* Shall not exceed the limits given in the detailed spec.
3.	Q/ D.F.	At 25℃ ambient temperature.	* 0402/25V~50V: Q≥400+20C
	(Dissipation		
	Factor)		
4.	Dielectric	*To apply voltage: 250% of rated voltage.	* No evidence of damage or flash over during test.
	Strength	*Duration: 1 to 5 sec.	
		*Charge & discharge current less than 50mA.	
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥100Ω-F whichever is smaller
	Resistance		
6.	Temperature	With no electrical load.	* Capacitance change: within ±30ppm/℃;
	Coefficient	Operating temperature: -55~125℃ at 25℃	
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	Strength of	0402 to 0603: 5N	
	Termination	* Test time: 10±1 sec.	7
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.
		* Test time: 6 hrs. (Two hrs each in three mutually	
		perpendicular directions.)	(A) 5(,)
		*Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	미
9.	Solderability	* Solder temperature: 235±5°C	95% min. coverage of all metalized area.
J.	Solderability	* Dipping time: 2±0.5 sec.	IANCE SALE SALE SALE SALE SALE SALE SALE SAL
10.	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.
	<b>J</b>	of the pressurizing rod at a rate of about 1 mm per second until	
		the deflection becomes 1 mm and then the pressure shall be	(This capacitance change means the change of capacitance under
		maintained for 5±1 sec.	specified flexure of substrate from the capacitance measured before
		* Measurement to be made after keeping at room temp. for	the test.)
		24±2 hrs.	1101.
11.	Resistance to	* Solder temperature: 260±5°C	* No remarkable damage.
	Soldering Heat	* Dipping time: 10±1 sec	* Cap change: within ±2.5% or ±0.25pF whichever is larger.
		* Preheating: 120 to 150℃ for 1 minute before imme rse the	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		capacitor in a eutectic solder.	* 25% max. leaching on each edge.
		*Cap. / DF(Q) / I.R. Measurement to be made after de-aging at	
		150℃ for 1hr then set for 24±2 hrs at room temp.	

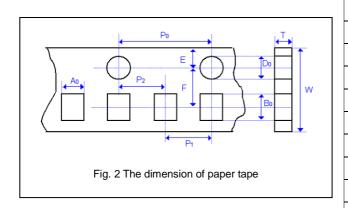
## **Multilayer Ceramic Capacitors**

No.	Item	Test Condition	Requirements
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time.	No remarkable damage. Cap change: within ±2.5% or ±0.25pF whichever is larger.
	Gyote	Step         Temp. (℃)         Time (min.)           1         Min. operating temp. +0/-3         30±3           2         Room temp.         2~3           3         Max. operating temp. +3/-0         30±3           4         Room temp.         2~3           * Cap. / DF(Q) / I.R. Measurement to be made after de-aging 150℃ for 1hr then set for 24±2 hrs at room temp.         150℃ for 1hr then set for 24±2 hrs at room temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
13.	Humidity (Damp Heat) Steady State	* Test temp.: 40±2°C  * Humidity: 90~95% RH  * Test time: 500+24/-0hrs.  * Cap. / DF(Q) / I.R. Measurement to be made after de-aging 150°C for 1hr then set for 24±2 hrs at room temp.	* No remarkable damage.  * Cap change: within ±5.0% or ±0.5pF whichever is larger.  * Q/D.F. value: Q≥200+10C  * I.R.: ≥1GΩ.
14.	Humidity (Damp Heat) Load	* Test temp.: 40±2°C  * Humidity: 90~95%RH  * Test time: 500+24/-0 hrs.  * To apply voltage: rated voltage  * Cap. / DF(Q) / I.R. Measurement to be made after de-aging	* No remarkable damage.  * Cap change: within ±7.5% or ±0.75pF whichever is larger.  * Q/D.F. value: Q≥100+10/3C  * I.R.: ≥500MΩ. g at
	High Temperature Load (Endurance)	* Test temp.: 125±3°C  * To apply voltage: 200% of rated voltage.  * Test time: 2000+24/-0 hrs.  * Cap. / DF(Q) / I.R. Measurement to be made after de-aging 150°C for 1hr then set for 24±2 hrs at room temp  The ESR should be measured at room temperature and test at frequency 1±0.1 GHz.	tied 0402 0.05pF≤Cap≤1pF:< 350mΩ/pF 1pF <cap≤5pf:< 300mω<="" th=""></cap≤5pf:<>
		Opyright Signature of the Control of	<u>5pF<cap≤100pf:< 250mω<="" u=""></cap≤100pf:<></u>

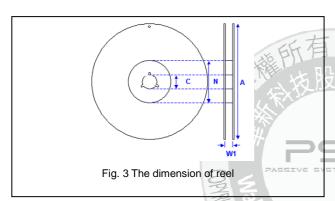
#### Approval Sheet

# **APPENDIXES**

## **■ Tape & reel dimensions**

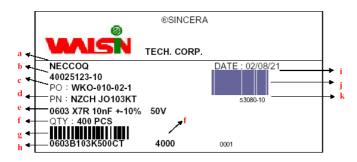


Size	0402
Thickness	N
$A_0$	0.70 +/-0.20
B <sub>0</sub>	1.20 +/-0.20
Т	≦0.80
$K_0$	-
W	8.00 +/-0.30
P <sub>0</sub>	4.00 +/-0.10
10xP <sub>0</sub>	40.00 +/-0.10
P <sub>1</sub>	2.00 +/-0.05
P <sub>2</sub>	2.00 +/-0.05
D <sub>0</sub>	1.50 +0.1/-0
D <sub>1</sub>	-
13 E	1.75 +/-0.10
A	3.50 +/-0.05



Size	0402		
Reel size	7"	13"	
С	13.0+0.5/-0.2	13.0+0.5/-0.2	
W <sub>1</sub>	8.4+1.5/-0	8.4+1.5/-0	
EM AIA TANC	178.0±1.0	330.0±1.0	
N	60.0+1.0/-0	100±1.0	

# **■** Example of customer label

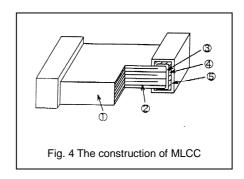


\*Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

#### Constructions

No.	Na	NP0	
1)	Ceramic material		Hi-Q dielectric ceramic
2	Inner electrode		Cu
3		Inner layer	Cu
4	Termination	Middle layer	Ni
(5)		Outer layer	Sn (Matt)



#### Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

#### Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



#### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N<sub>2</sub> within oven are recommended.

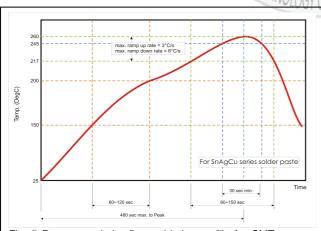


Fig. 5 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.